

# Electromagnetic Shielding of Plastic Packaging in Cost-Effective Optical Transceiver Modules

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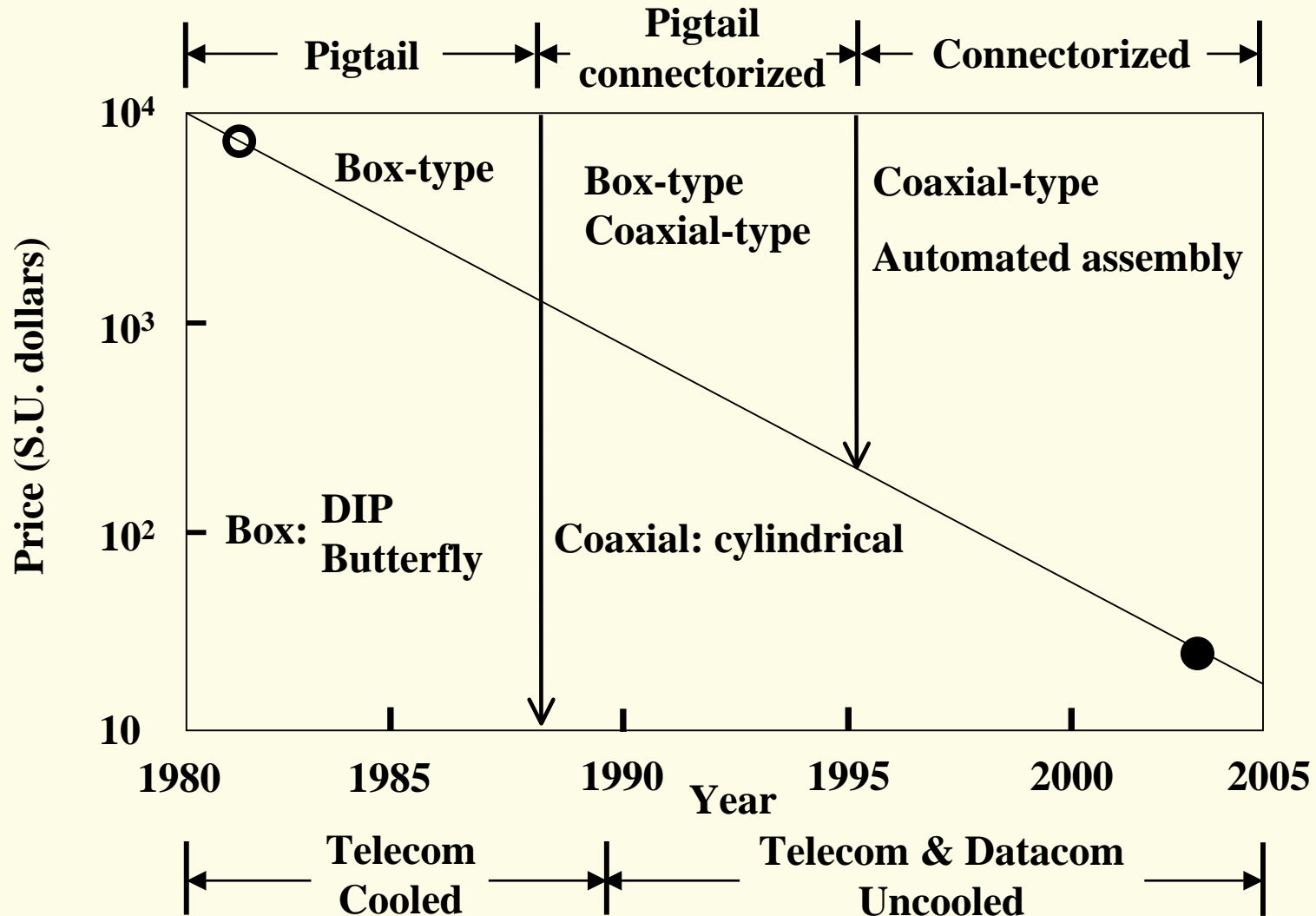
# **Objective of Study**

**To develop the plastic optical transceiver modules with low cost and low electromagnetic interference (EMI) for use in Gigabit Ethernet or fiber to the home (FTTH) lightwave communication systems**

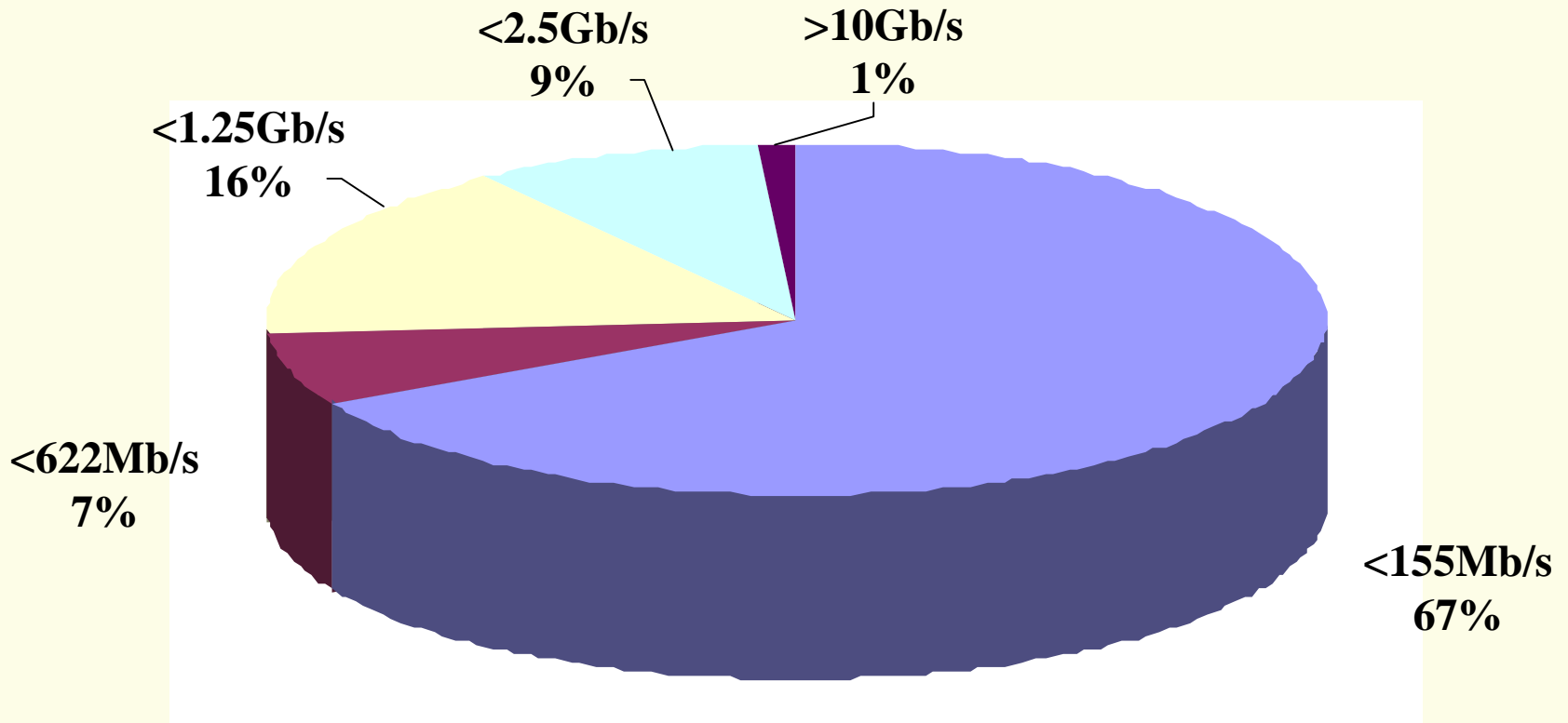
# Outline

- 1. Motivation**
- 2. Fabrication and Shielding Performance of Plastic Composites with Discontinuous Carbon Fiber Fillers**
- 3. Fabrication and Shielding Performance of Plastic Composites with Continuous Carbon Fibers**
- 4. Fabrication and Shielding Performance of Hollow Carbon Nanocapules**
- 5. Comparison of Fabrication and Shielding Performance for Plastic Composites and Plastic Optical Transceiver Modules**
- 6. Conclusion**

# Low Cost Laser Module Packages

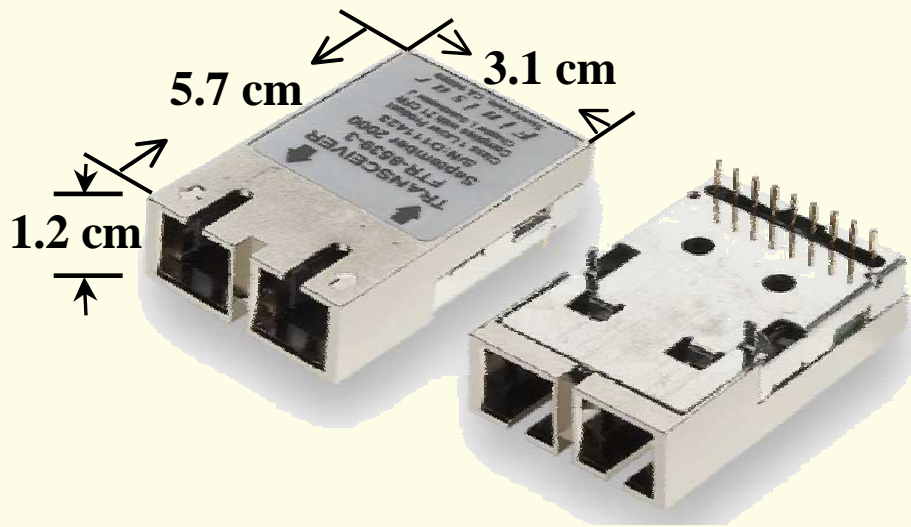


# Transceiver Module Market

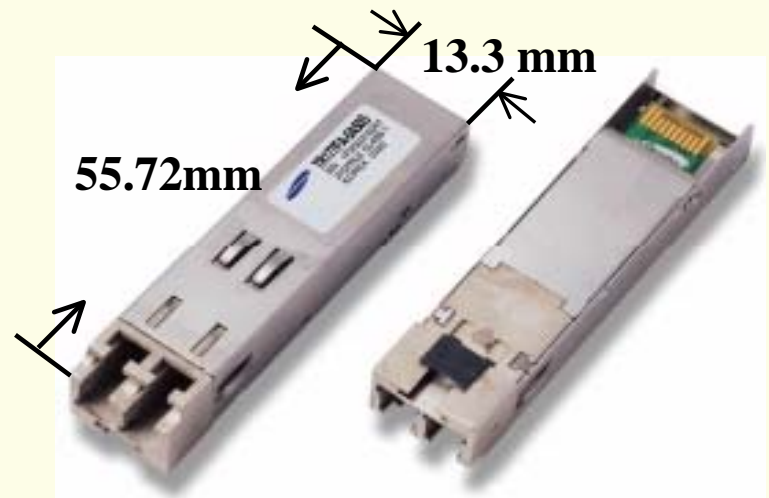


# Optical Transceiver Module

Data Rate : 155Mb/s → 1.25Gb/s → 2.5Gb/s

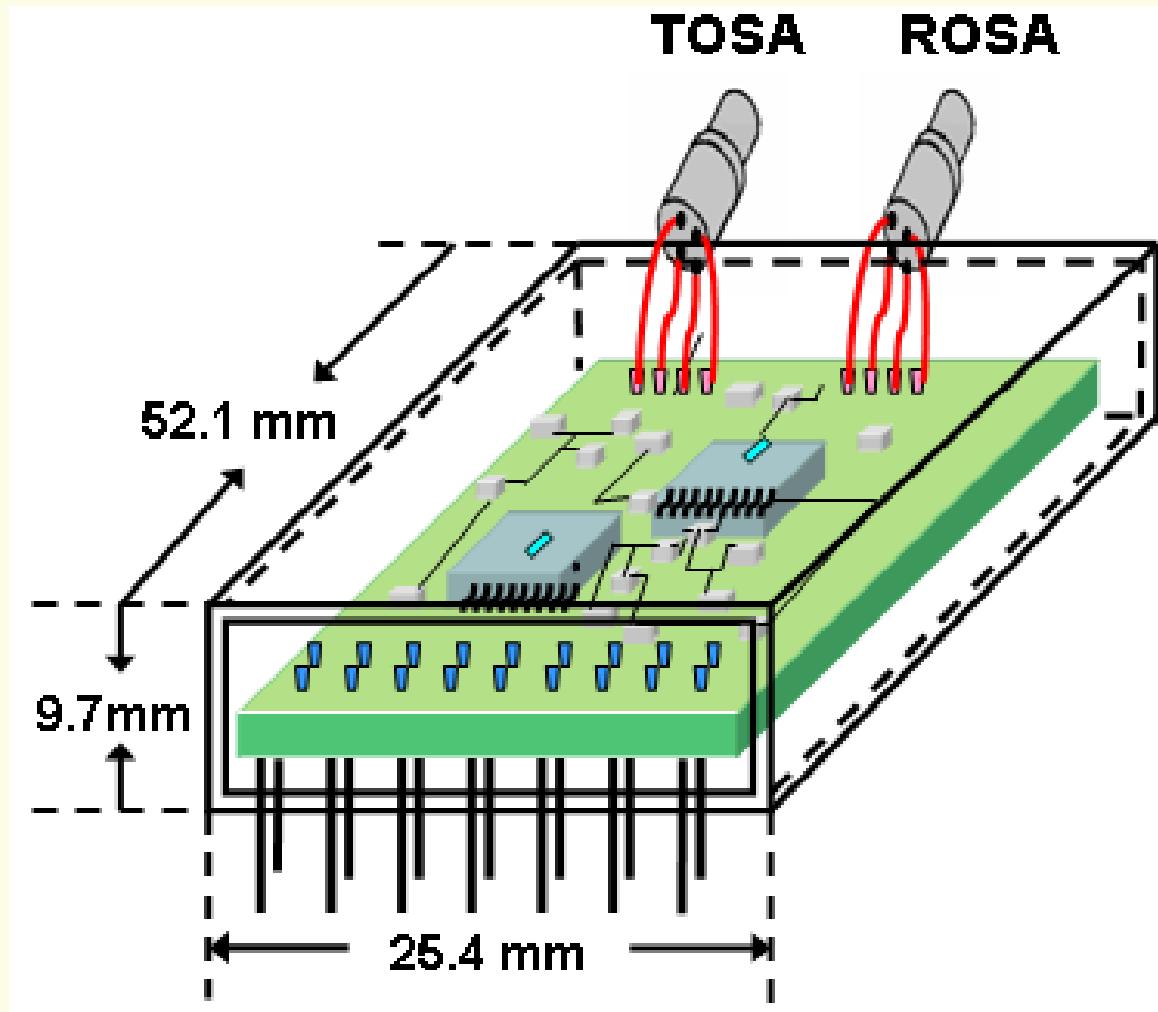


**1X9 Type**



**Height = 8.55 mm**  
**Small Form Factor Pluggable (SFP)**

# Frame of Transceiver Module



# Techniques for plastic EM shielding

- Conductive sprays
- Conductive fillers
- Zinc-arc spraying
- Electro-plating or electrolysis-plating on housing surfaces
- Modifications of electrical properties during the molding stage
- Metallization processes



# Conductive fillers for EM shielding

- Metal particles
- Metal flakes
- Stainless fiber
- Graphitized carbon particles
- Graphitized carbon fibers
- Metal-coated glass
- Carbon fibers

# Fabrication of plastic composites



**1.Twin-Screw Extruder**



**2.Injection-Molded Machine**

**Process:**

Plastic materials



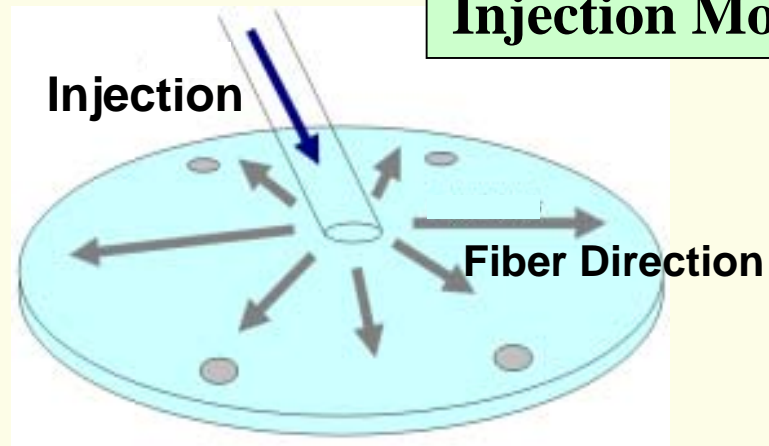
Carbon fibers



Plastic composites

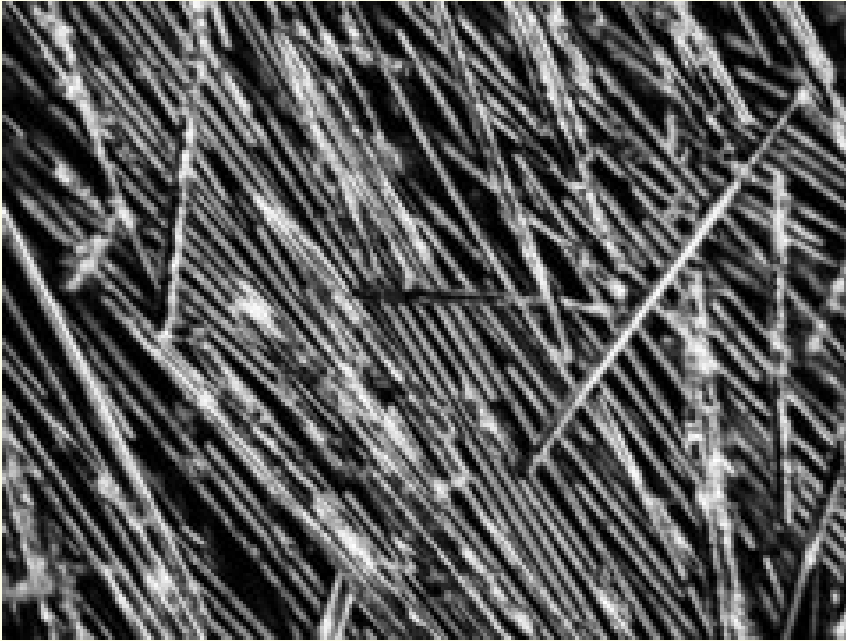


Injection Molding



**3.specimen**

# Metallographic



**LCP :**

→ with 25% carbon fiber

→ orientation uniform

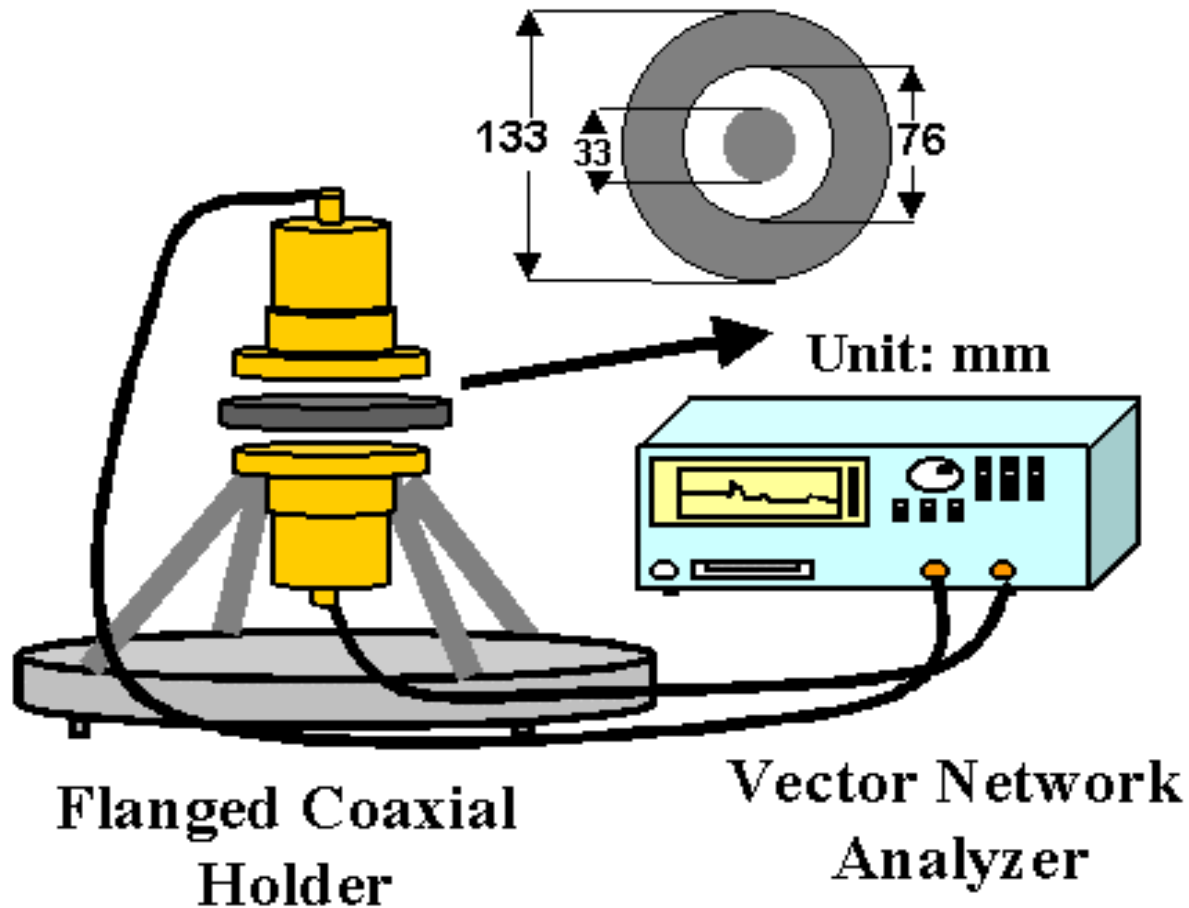


**Nylon :**

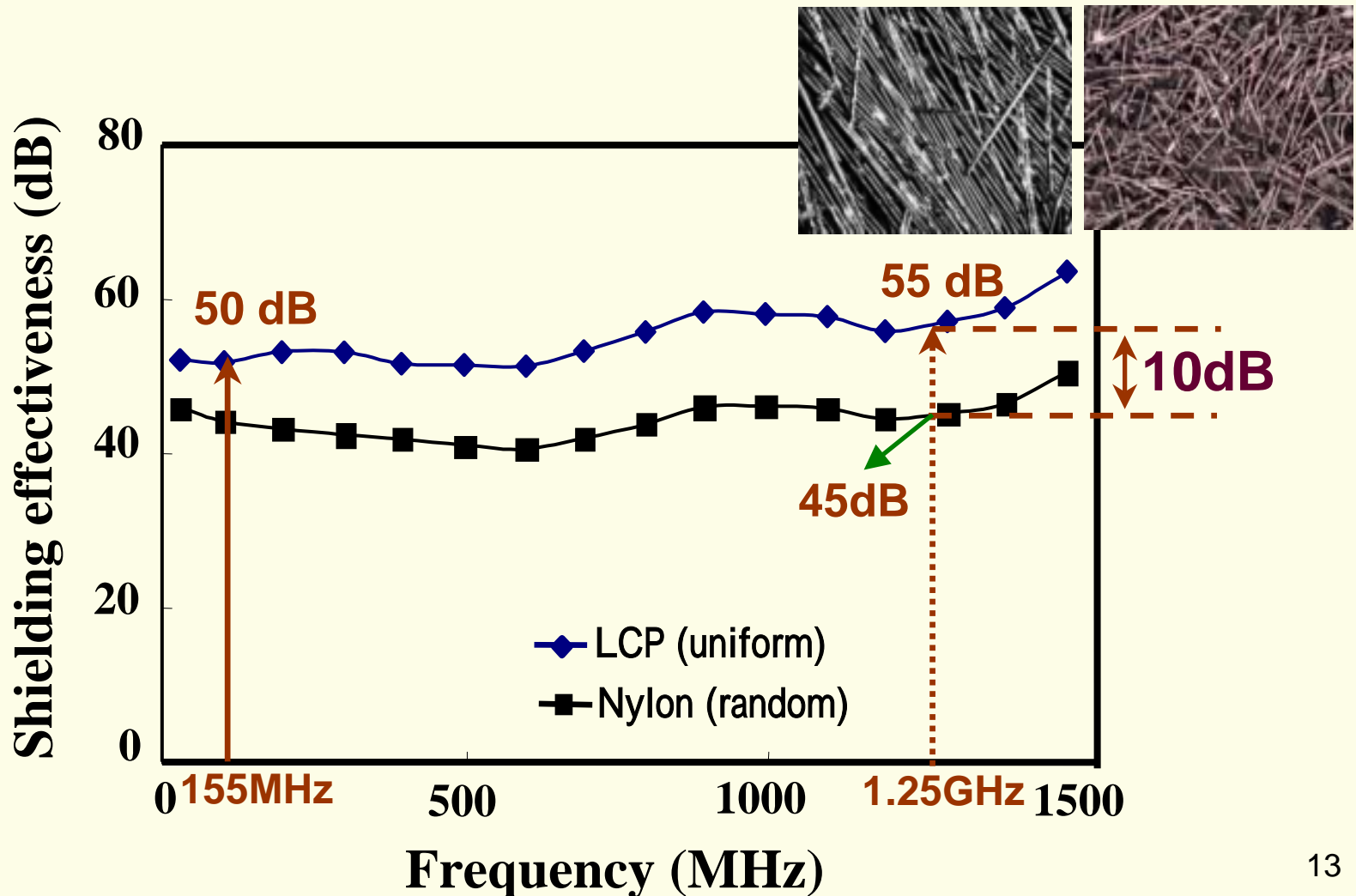
→ with 25% carbon fiber

→ orientation random

# Measurement Setup



# LCP and Nylon Composites



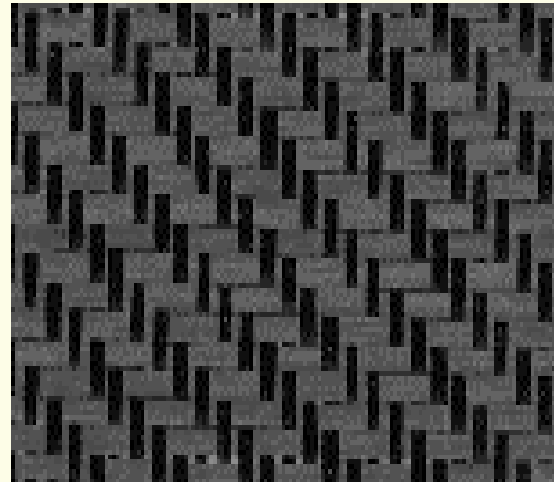
# **Woven Continuous Carbon Fiber Fabrics**

## **Advantages :**

- 1. continuous carbon fiber**
- 2. complete conductive networks**
- 3. easy fabrication and low cost**



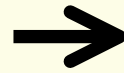
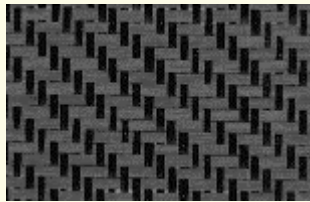
**Polymer composites**



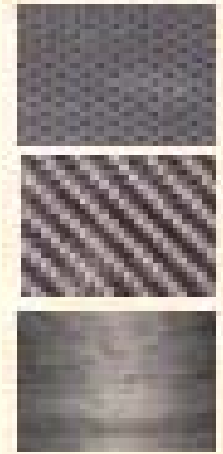
**Fabrics**

# Fabrication of WCC Fabrics

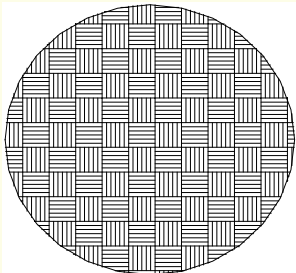
**Different Weave Methods**



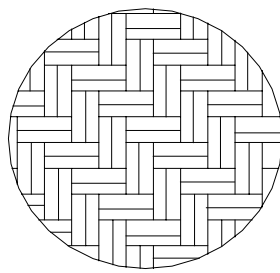
**Epoxy**



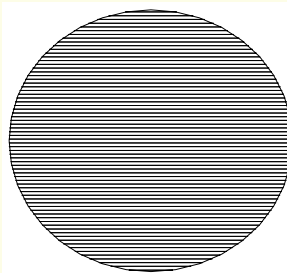
**Test samples**



**Plain**



**Balanced Twill**

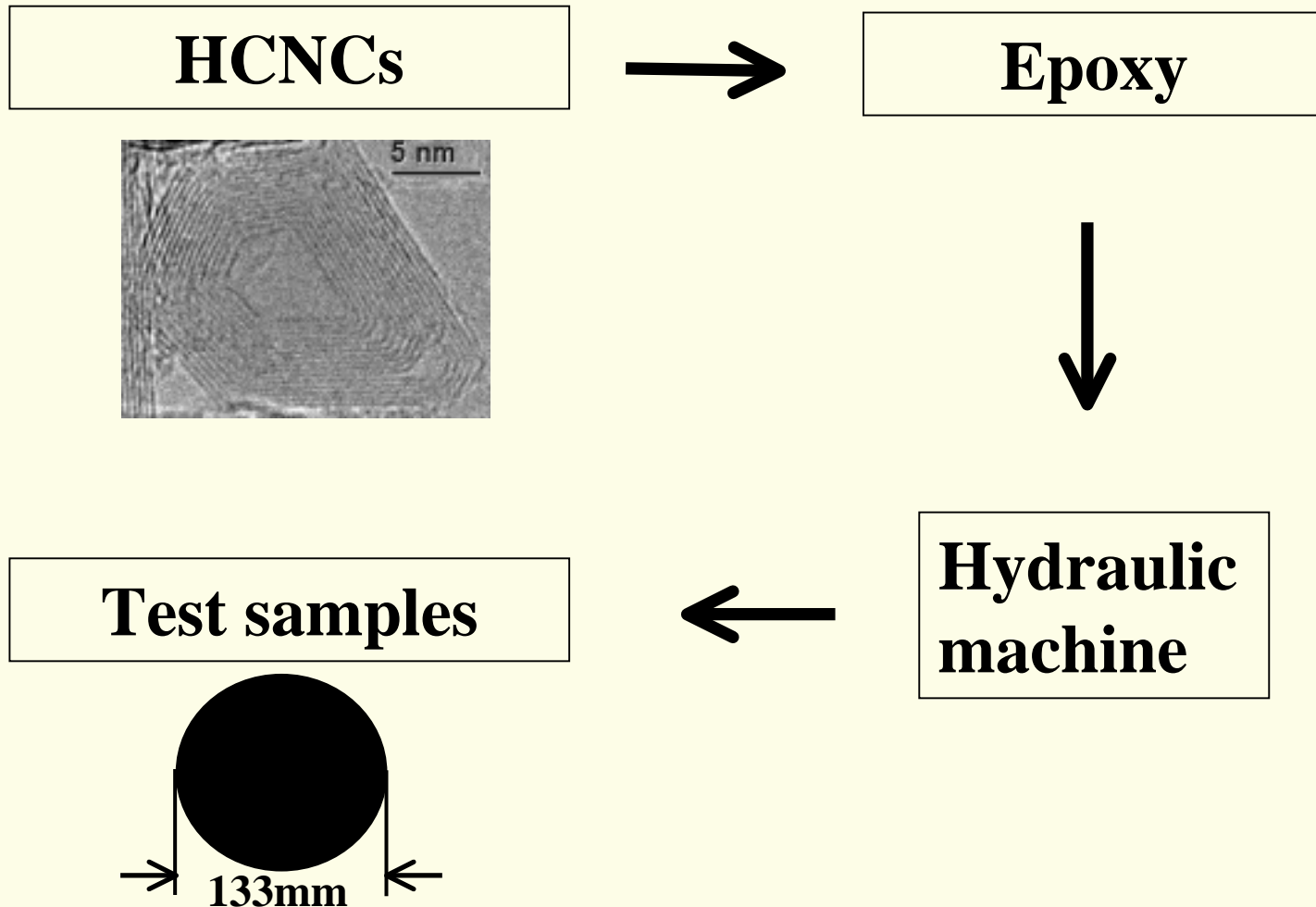


**Uni-direction**

**Compression  
molding  
machine**



# Fabrication of HCNCs Composites

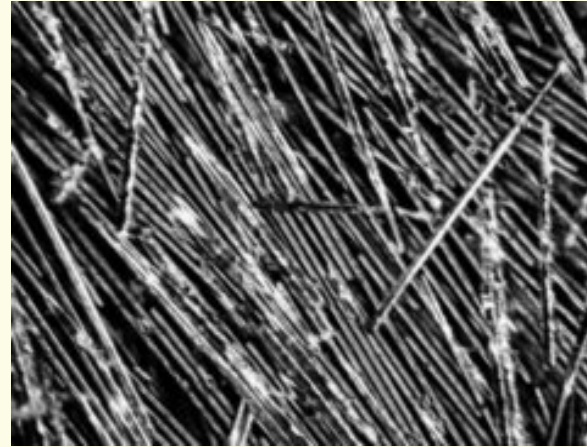




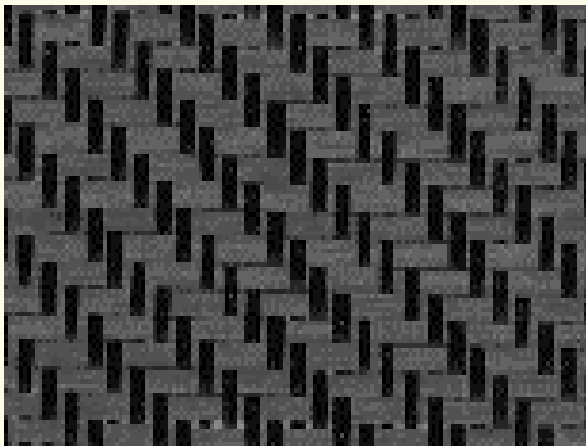
# Metallographic



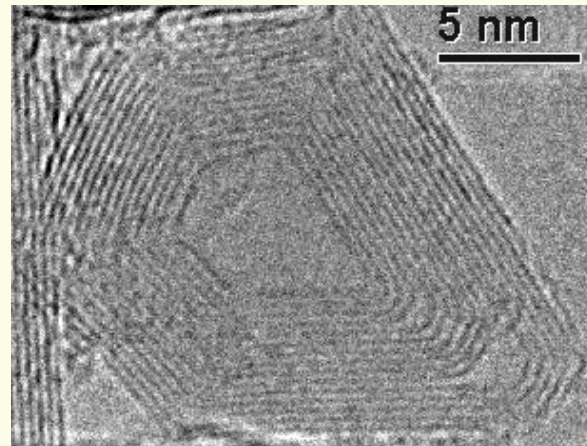
**(a) Nylon**



**(b) LCP**

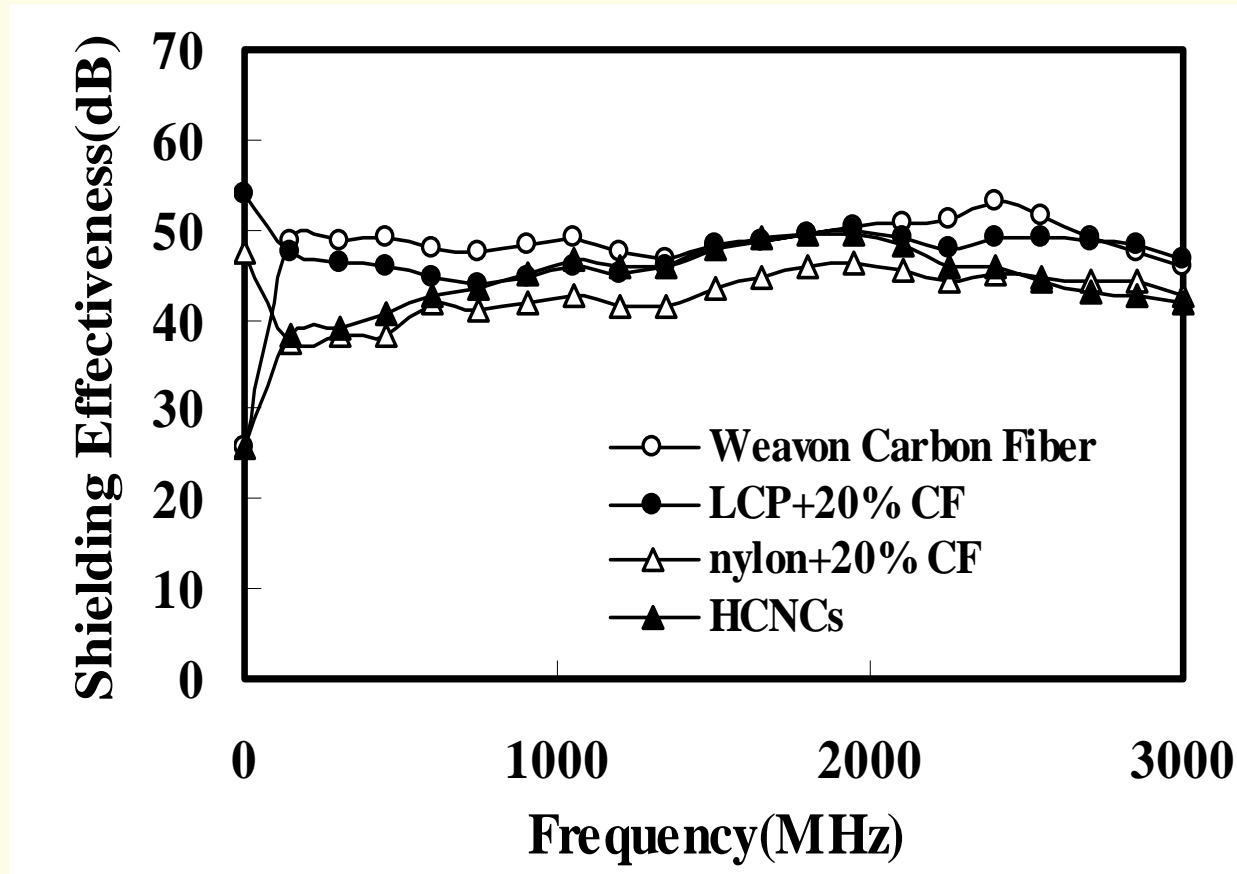


**(c) WCCF**

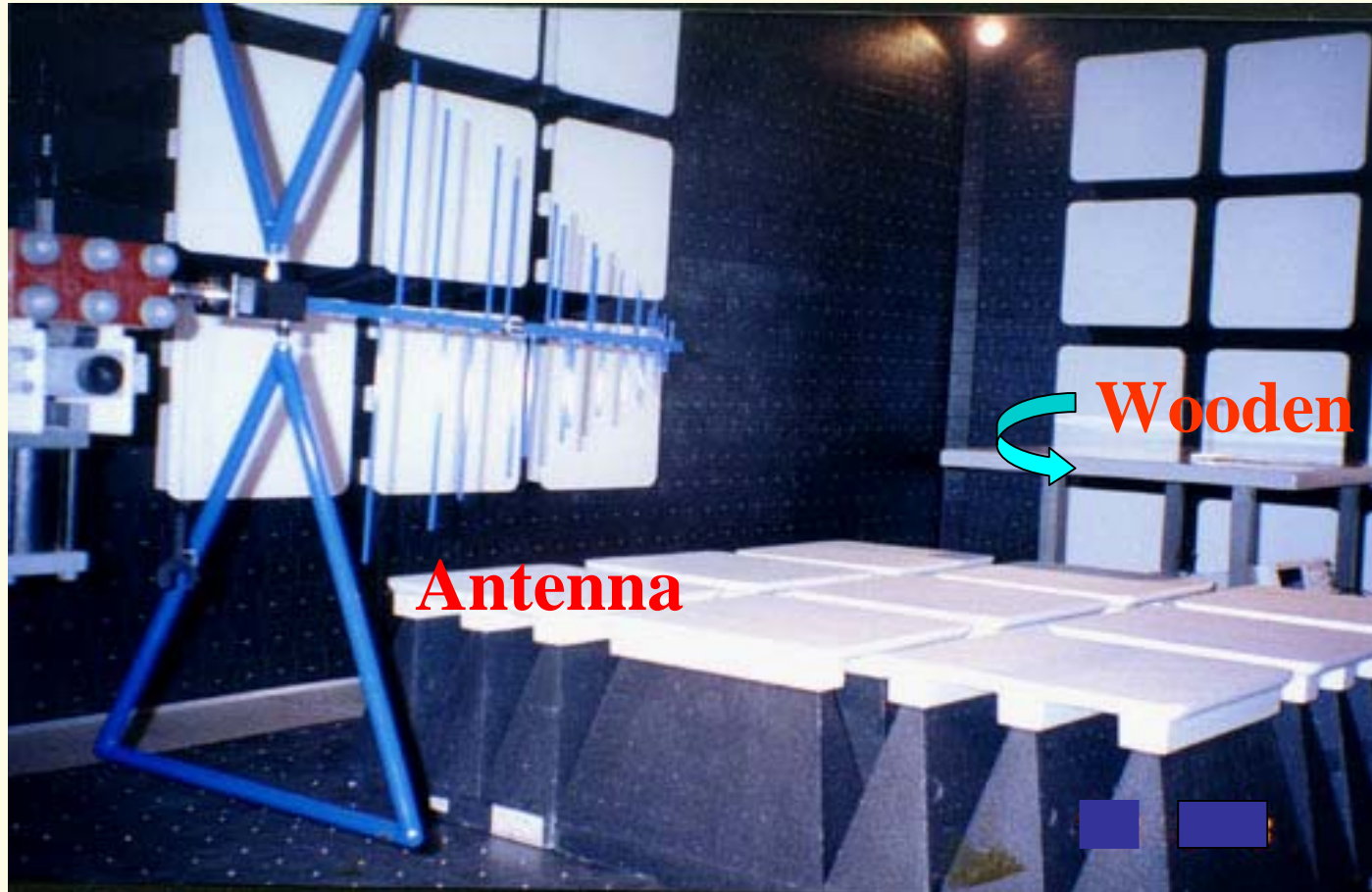


**(d) HCNC**

# Comparison of SE Performance of Nylon, LCP, WCCF and HCNCs Composites

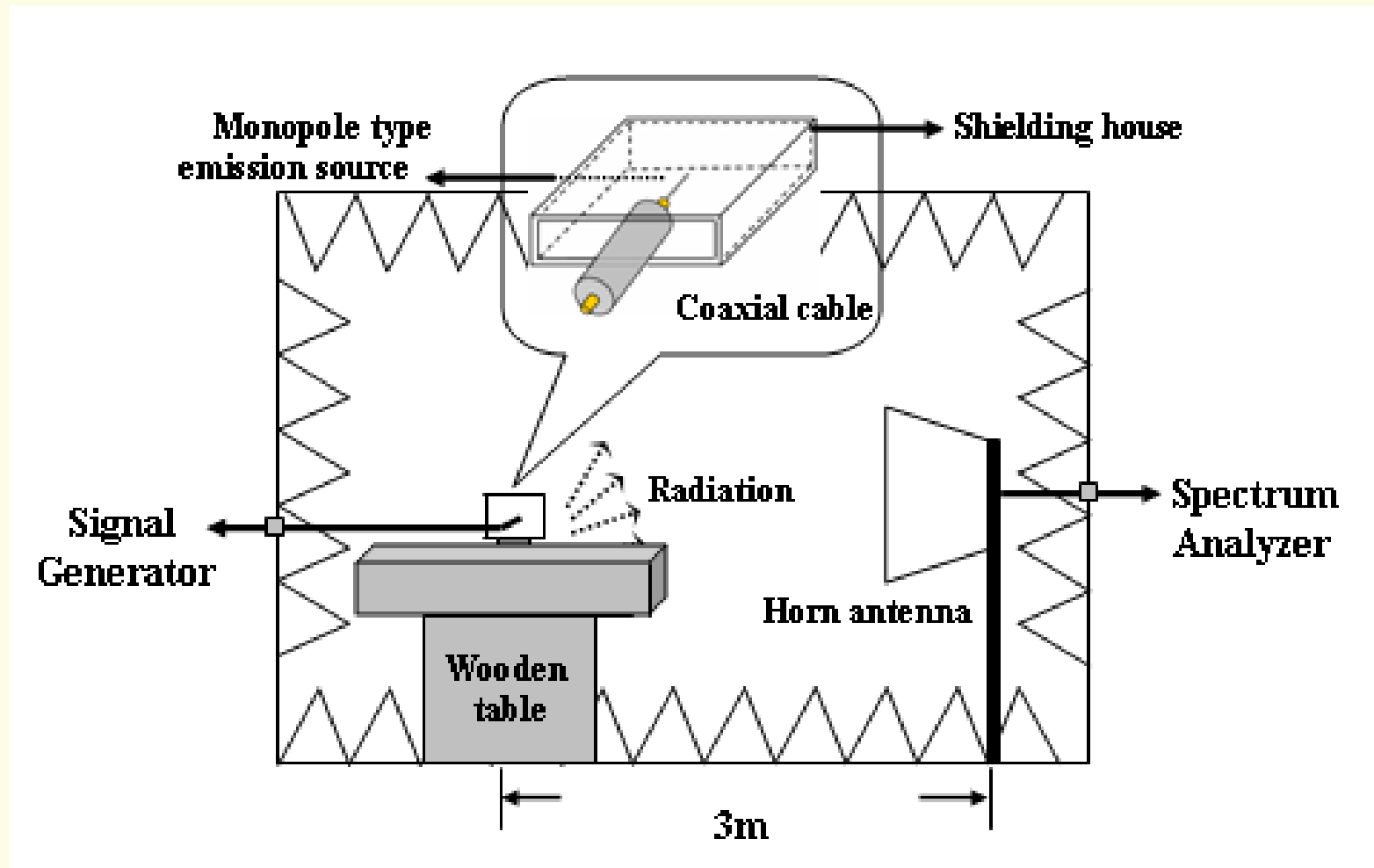


# Anechoic Chamber

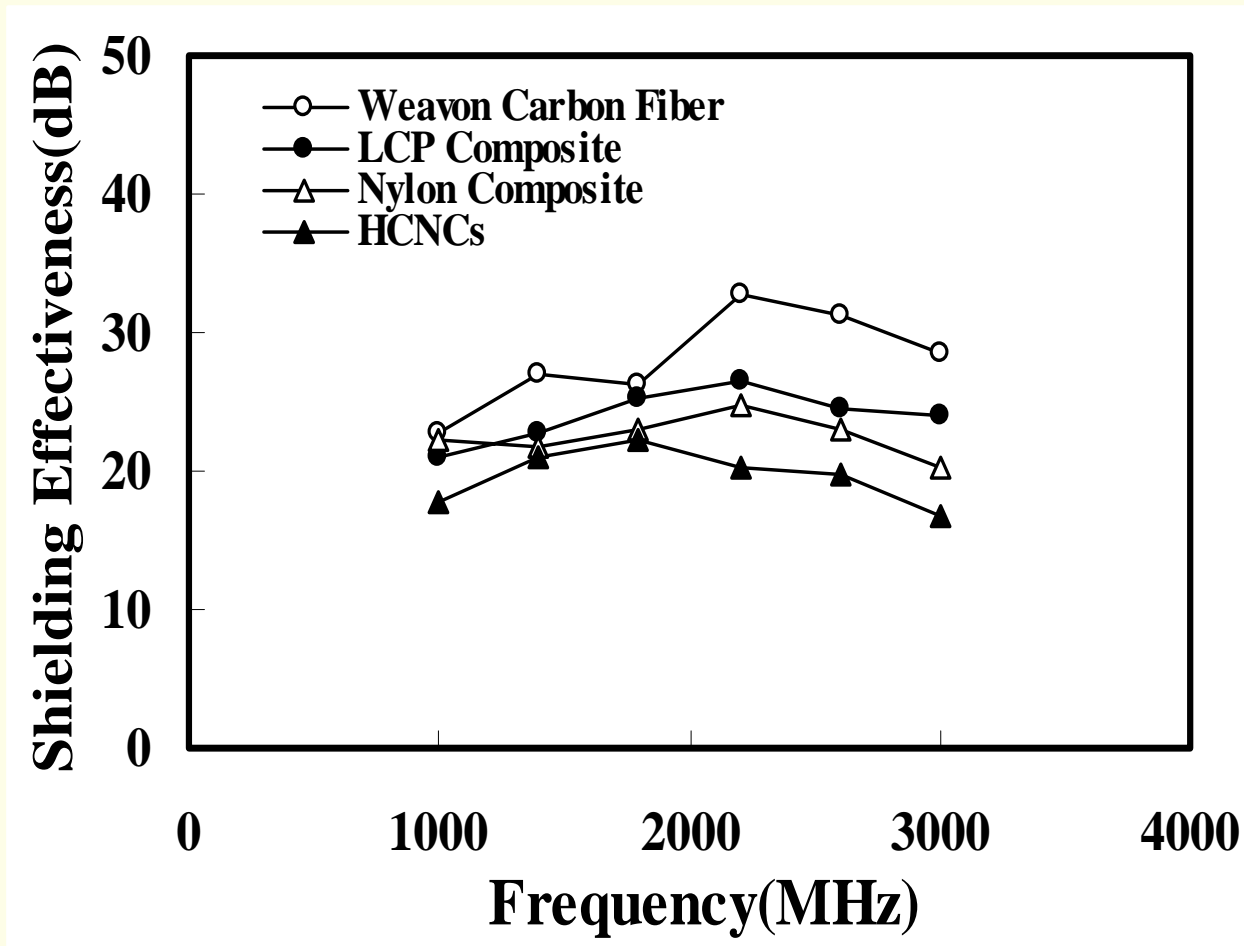


Chamber volume = 7m x 4m x 3m

# S.E. measurement for near-field monopole-type source in a fully anechoic EMC chamber



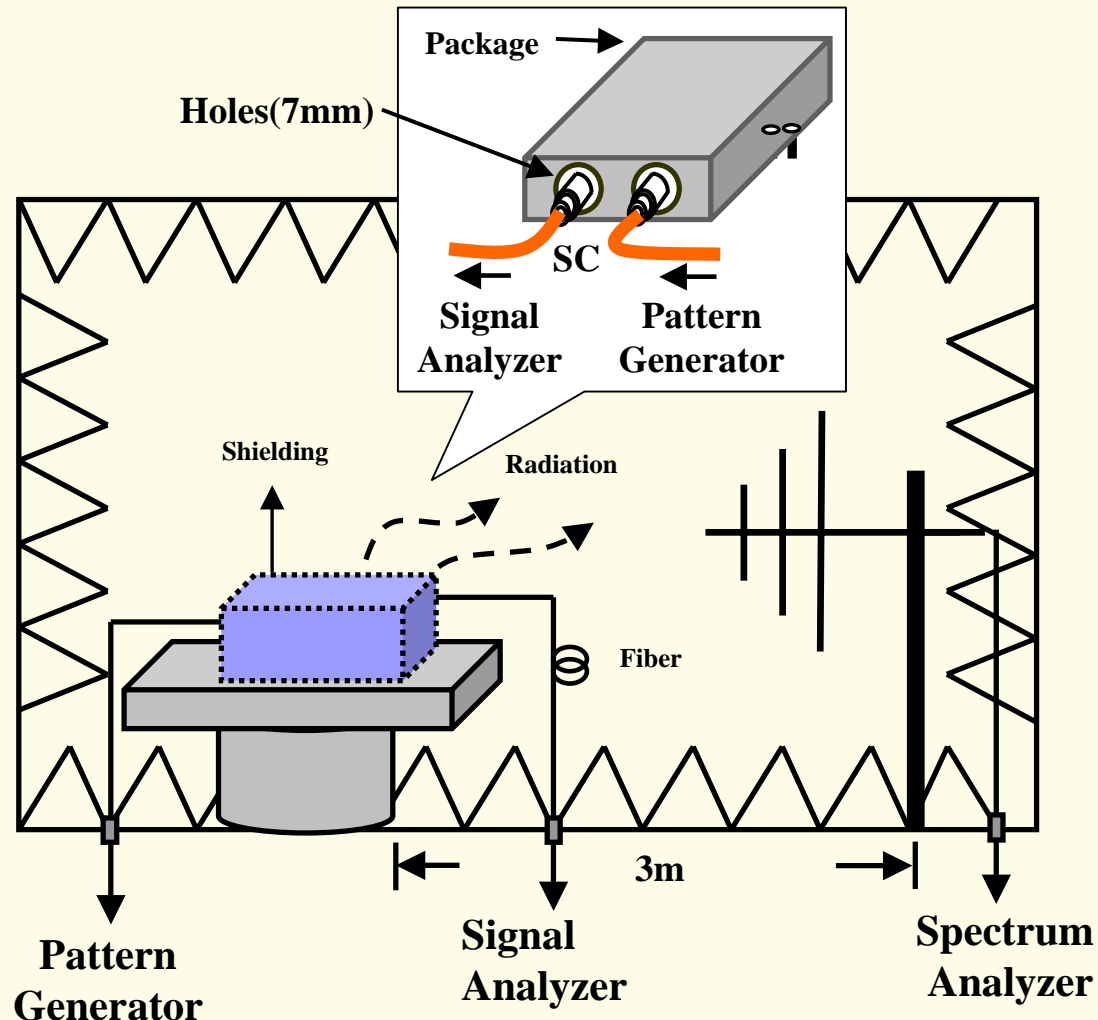
# Comparison of SE performance of realistic housings fabricated by HCNCs composites



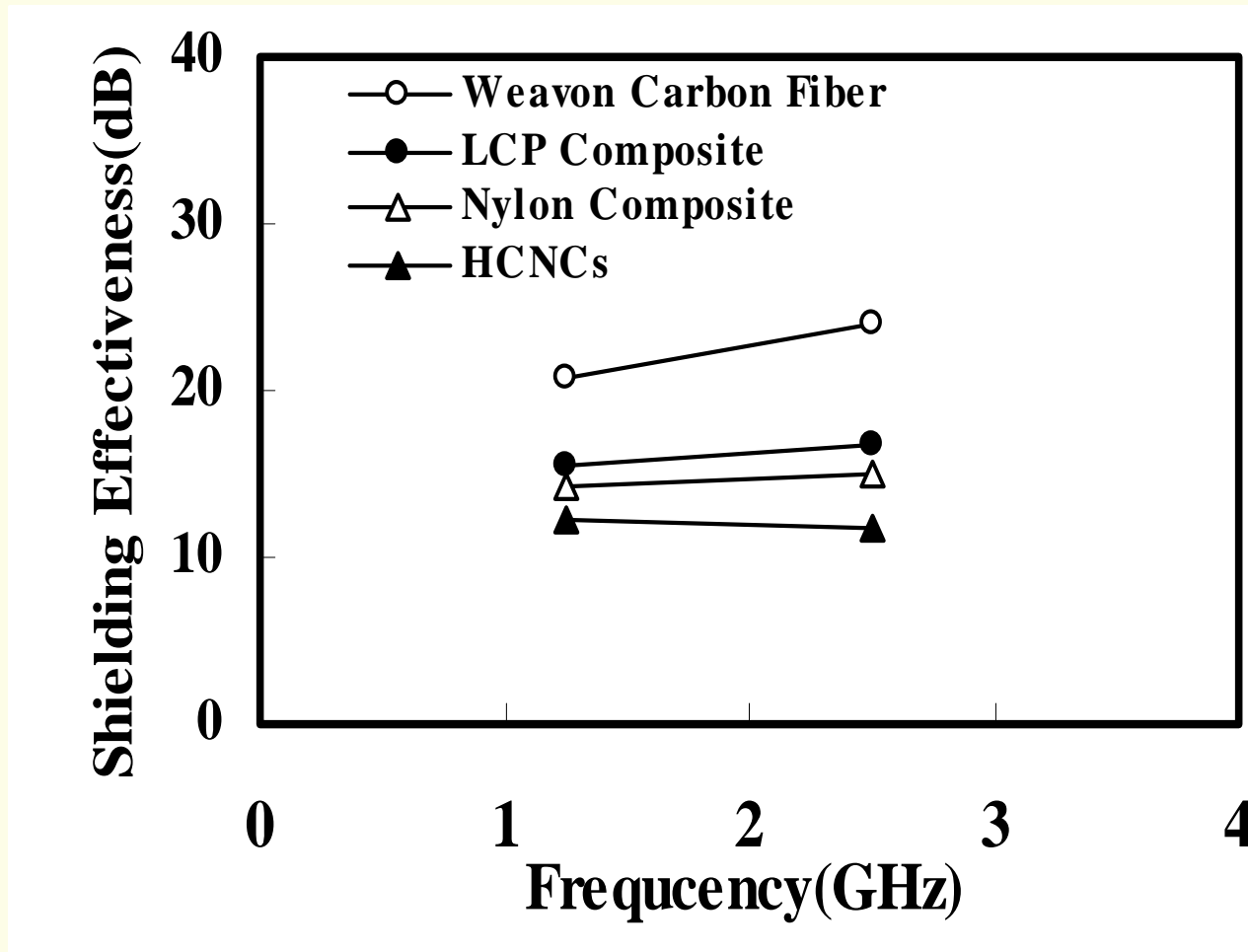
# Comparison of cost, and shielding performance of plastic composites

Sample	Material (Cost/g)	Filler (Cost/g)	Weight of Filler (g)	Total Weight ( g )	Thickness of Sample (mm)	Cost of Sample (US)	SE (dB)
Nylon Composite	Nylon-66 ( $8.8 \times 10^{-3}$ )	Carbon Fiber ( $2.3 \times 10^{-2}$ )	16.6	83	3	0.96	40~50
LCP Composite	LCP ( $2.3 \times 10^{-2}$ )	Carbon Fiber ( $2.3 \times 10^{-2}$ )	16.6	83	3	1.91	40~50
Weavon Carbon Fiber	Epoxy ( $8.8 \times 10^{-3}$ )	Carbon Fiber ( $2.3 \times 10^{-2}$ )	2	4	0.5	0.06	40~50
Carbon Nanocapsule	Epoxy ( $8.8 \times 10^{-3}$ )	Carbon Nanocapsule ( 5.88 )	7	9	0.5	41	40~50

# Measurement setup of the radiated emission for the optical transceiver module in normal operation

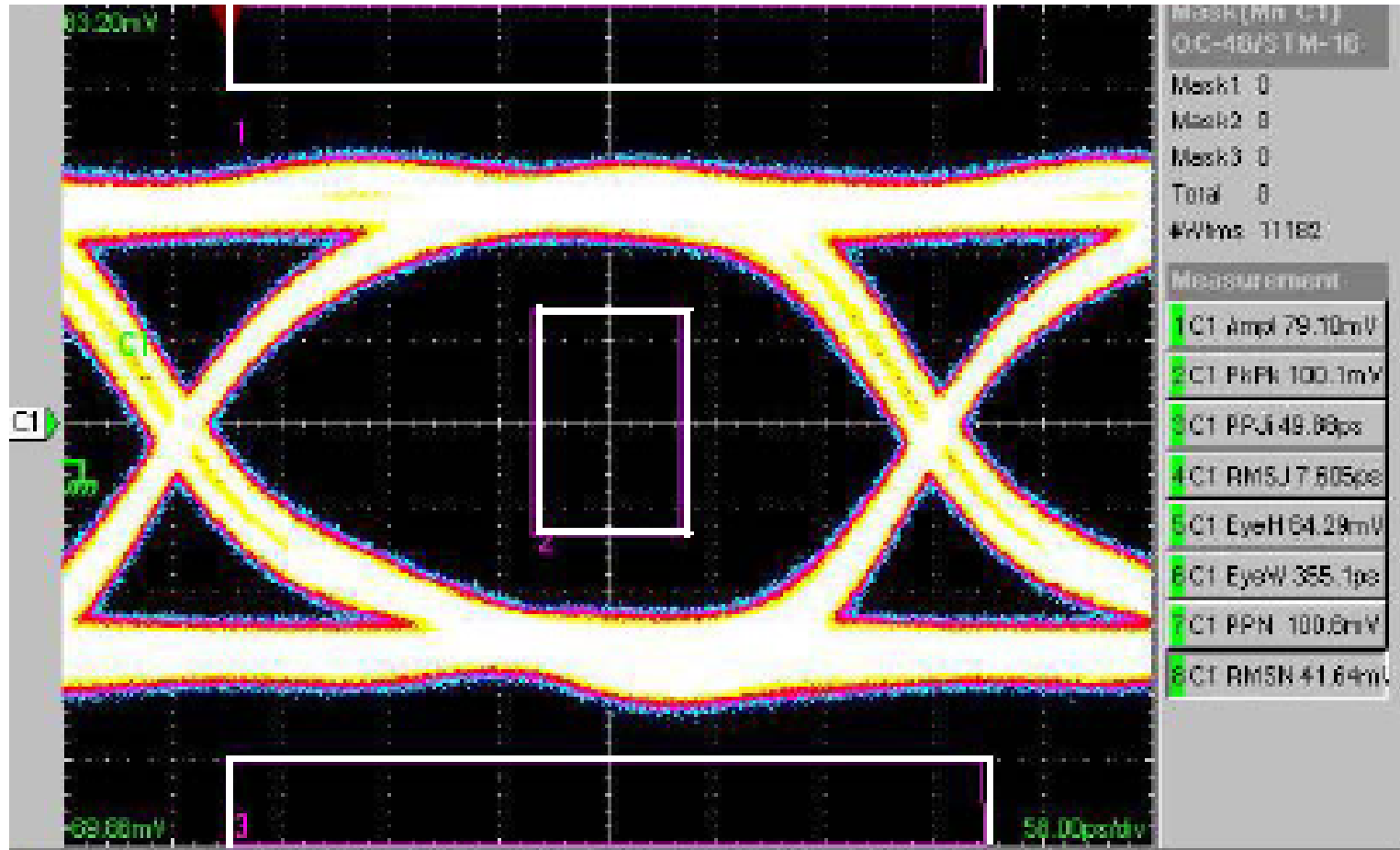


# Comparison of SE performance of optical transceiver modules at 1.25 GHz and 2.5 GHz fabricated by nylon, LCP, WCCF and HCNCs composites





# Eye Diagram of 2.5Gb/s Transmitter



# Comparison of cost, and shielding performance of optical transceiver modules

Sample	Material (Cost/g)	Filler (Cost/g)	Weight of Filler (g)	Total Weight ( g )	Thickness of Sample (mm)	Cost of Sample (US)	SE (dB)
<b>Nylon Composite</b>	Nylon-66 ( $8.8 \times 10^{-3}$ )	Carbon Fiber ( $2.3 \times 10^{-2}$ )	12.8	51.5	3	0.64	15
<b>LCP Composite</b>	LCP ( $2.3 \times 10^{-2}$ )	Carbon Fiber ( $2.3 \times 10^{-2}$ )	12.8	51.5	3	1.18	17
<b>Weavon Carbon Fiber</b>	Epoxy ( $8.8 \times 10^{-3}$ )	Carbon Fiber ( $2.3 \times 10^{-2}$ )	1.24	2.5	0.5	0.04	24
<b>Carbon Nanocapsule</b>	Epoxy ( $8.8 \times 10^{-3}$ )	Carbon Nanocapsule ( 5.88 )	6	8	0.5	35	12

# Conclusion

**Low-cost optical transceiver modules with transmission rates of 155Mb/s, 1.25Gb/s, and 2.5Gb/s were successfully fabricated to investigate the EM shielding ability.**

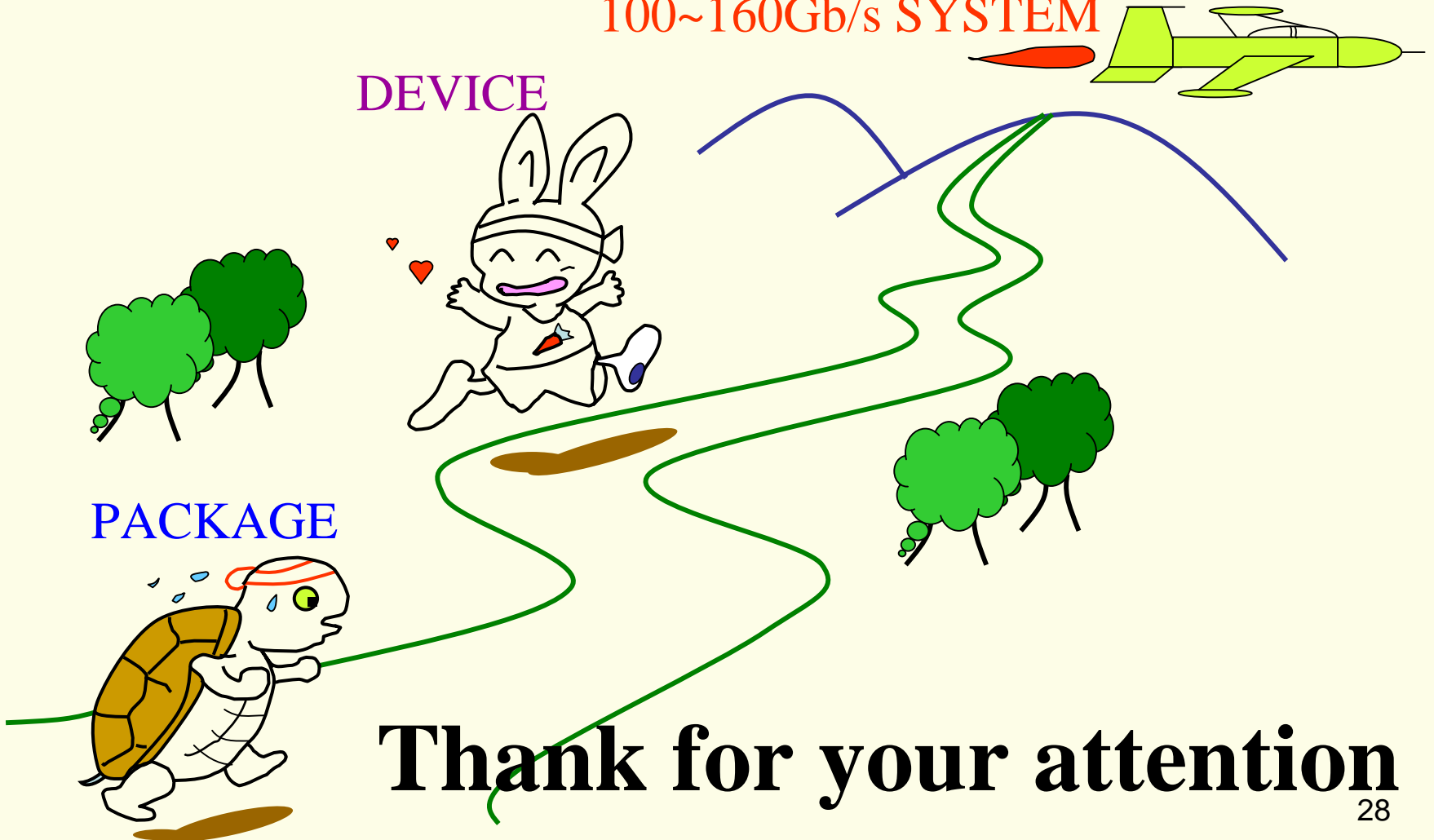
- The LCP composites perform better SE than the nylon66. This is the LCP polymer chains have higher ordering structure under both melting and solid state.**
- By comparison of cost, weight and shielding performance for optical transceiver modules fabricated by the housings of nylon, LCP, WCCF and HCNCs composites, the WCCF composite showed lower cost, lighter weight and higher EM shielding than the other types of composites.**
- Due to the fact that the electronic and mechanical properties of HCNCs composites are remarkable, future research and development may push to develop the low cost and low EMI optical transceiver modules using nanoscale HCNCs.**
- The packaged plastic optical transceiver modules with low cost and low EMI are suitable for use in Gigabit Ethernet or fiber to the home lightwave (FTTH) communication systems.**

# Turtle Spirit : Making a low-cost package affort step by step

100~160Gb/s SYSTEM

DEVICE

PACKAGE



# Thank for your attention